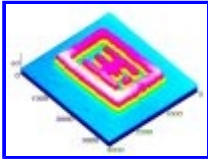
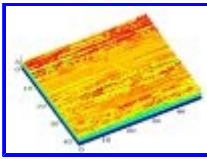


3D Museum

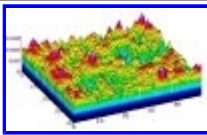
by SP-500 Surface Profiler

Please click to enlarge the image.

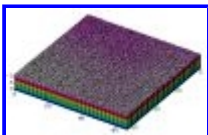

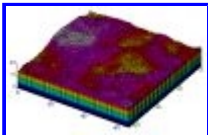
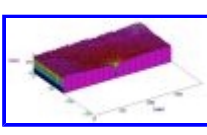
● Metals

					
Coin	VSI	FOV: 3.6mm Height: 50um	FD Metal Lid	VSI	FOV: Height: 1um

● Plastics

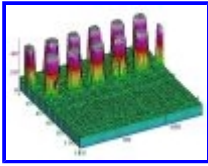
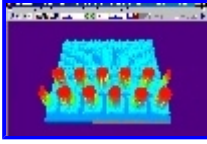
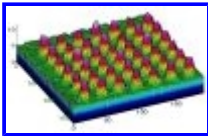
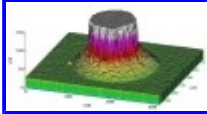
					
FD Media Surface	PSI	FOV: Height: 1um			

● Semiconductors/Wafers

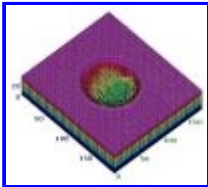
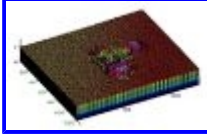
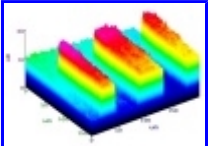
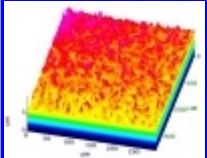
					
Si Wafer (Highly polished) Ra=0.36nm	PSI	FOV: 80um Height: 1nm	Si Wafer (Polished) Ra=0.65nm	PSI	FOV: 80um Height: 2nm
					
Si Wafer (Little polished)	PSI	FOV: 80um Height: 7nm	Si Wafer (Center)	PSI	FOV: 200um Height:

Ra=1.27nm					25nm
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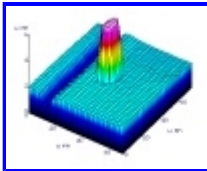
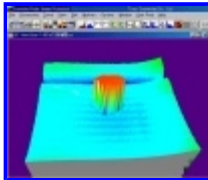
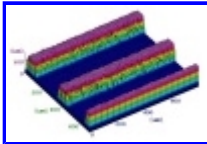
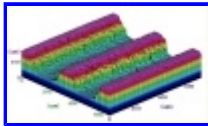
● **Semiconductors/Bumps**

					
Bump(Stud)	VSI	FOV: 0.8mm Height: 40um	Bump(Stud) imaged by "SPIP" software	VSI	FOV: 0.8mm Height: 40um
					
Bump(Grid)	VSI	FOV: 0.8mm Height: 5um	Bump(Cu)		FOV: .3mm Height: 100um

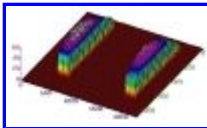
● **Semiconductors/Others**

					
Via Hole	VSI	FOV: 0.2mm Height: 15um	Probe Mark	VSI	FOV: 80um Height: 0.5um
					
Substrate Pattern	VSI	FOV: 0.2mm Height: 10um	Roughness	VSI	FOV: 0.3um Roughness:<1um

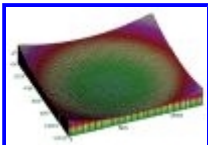
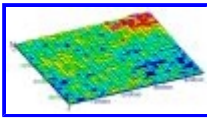
● **Flat Panel Display**

					
Column Spacer	VSI	FOV: 70um Height: 4um	Column Spacer imaged by "SPIP" software	VSI	FOV: 70um Height: 4um
					
PDP Rib	VSI	FOV: 700um Height: 100um	PDP Rib (with fluorescent agent)	VSI	FOV: 700um Height: 100um

● Magnetic Heads

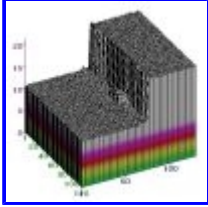
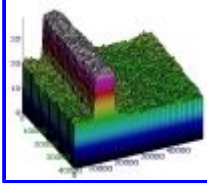
					
Head ABS Surface	PSI	FOV: 2.2mm Height: 20nm			

● Optical Parts

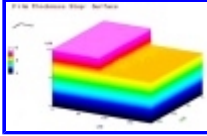
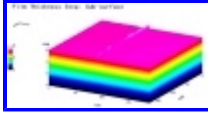
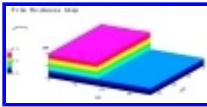
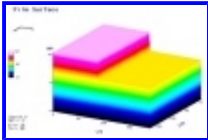
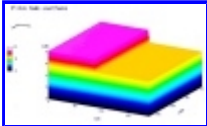
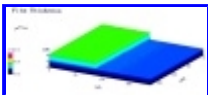
					
Lens	PSI	FOV: Height: 1um	Optical Flat Ra=0.4nm	PSI	FOV: 1.8mm Height: 1.5nm

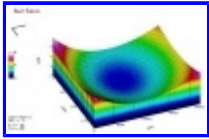
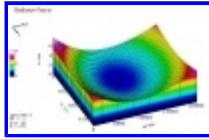
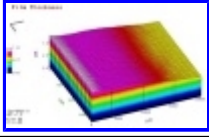
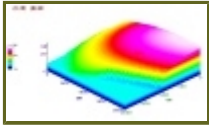
● Step Height

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10um Step Height	VSI	FOV: 0.8mm Height: 10um	20nm Step Height	PSI	FOV: 0.8mm Height: 20nm

Film Thickness *NEW*

					
Film Step Wafer #1 /Surface	VSI for Film	FOV: 0.19mm Step Height: 2.9um	Film Step Wafer #1 /Bottom Surface	VSI for Film	FOV: 0.19mm Step Height: 0.0um
					
Film Step Wafer #1 /Thickness	VSI for Film	FOV: 0.19mm Film Thickness: 4.1um/1.1um			
					
Film Step Wafer #2 /Surface	VSI for Film	FOV: 0.19mm Step Height: 3.3um	Film Step Wafer #2 /Bottom Surface	VSI for Film	FOV: 0.19mm Step Height: 2.2um
					

Film Step Wafer #2 /Thickness	VSI for Film	FOV: 0.19mm Film Thickness:2.1um/1.0um			
					
Film Slope Wafer /Surface	VSI for Film	FOV: 22mm	Film Slope Wafer /Subsurface	VSI for Film	FOV: 22mm
					
Film Slope Wafer /Thickness	VSI for Film	FOV: 22mm Thickness: 0.7-1.4um			
 NEW					
Water Surface	VSI for Film	FOV: 2mm Thickness: 0-20um			

● Cell Gap

					
LCD Cell Gap	VSI for Film	FOV: 22mm Cell Gap: 8.0-8.8um			

● [pdf file of this page \(270KB\)](#)


● Related products and technology

[SP-500 \(Surface Profiler\)](#)

[SP-500B \(Wafer Bump Inspection System\)](#)

[SP-500P \(Panel Surface Profiling System\)](#)

[Technology of Interferometric Surface Profiler](#) (Sorry in Japanese)

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